



Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Complete Data Sheet

DS083 (v5.0) June 21, 2011

Product Specification

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IMPORTANT NOTE: Page, figure, and table numbers begin at 1 for each module, and each module has its own Revision History at the end. Use the PDF "Bookmarks" pane for easy navigation in this volume.



Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Introduction and Overview

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Product Specification

Summary of Virtex-II Pro™ / Virtex-II Pro X Features

- High-Performance Platform FPGA Solution, Including
 - Up to twenty RocketIO™ or RocketIO X embedded Multi-Gigabit Transceivers (MGTS)
 - Up to two IBM PowerPC™ RISC processor blocks
- Based on Virtex-II™ Platform FPGA Technology
 - Flexible logic resources
 - SRAM-based in-system configuration
 - Active Interconnect technology
- SelectRAM™+ memory hierarchy
- Dedicated 18-bit x 18-bit multiplier blocks
- High-performance clock management circuitry
- SelectIO™-Ultra technology
- XCITE Digitally Controlled Impedance (DCI) I/O

Virtex-II Pro / Virtex-II Pro X family members and resources are shown in [Table 1](#).

Table 1: Virtex-II Pro / Virtex-II Pro X FPGA Family Members

Device ⁽¹⁾	RocketIO Transceiver Blocks	PowerPC Processor Blocks	Logic Cells ⁽²⁾	CLB (1 = 4 slices = max 128 bits)		18 X 18 Bit Multiplier Blocks	Block SelectRAM+		DCMs	Maximum User I/O Pads
				Slices	Max Distr RAM (Kb)		18 Kb Blocks	Max Block RAM (Kb)		
XC2VP2	4	0	3,168	1,408	44	12	12	216	4	204
XC2VP4	4	1	6,768	3,008	94	28	28	504	4	348
XC2VP7	8	1	11,088	4,928	154	44	44	792	4	396
XC2VP20	8	2	20,880	9,280	290	88	88	1,584	8	564
XC2VPX20	8 ⁽⁴⁾	1	22,032	9,792	306	88	88	1,584	8	552
XC2VP30	8	2	30,816	13,696	428	136	136	2,448	8	644
XC2VP40	0 ⁽³⁾ , 8, or 12	2	43,632	19,392	606	192	192	3,456	8	804
XC2VP50	0 ⁽³⁾ or 16	2	53,136	23,616	738	232	232	4,176	8	852
XC2VP70	16 or 20	2	74,448	33,088	1,034	328	328	5,904	8	996
XC2VPX70	20 ⁽⁴⁾	2	74,448	33,088	1,034	308	308	5,544	8	992
XC2VP100	0 ⁽³⁾ or 20	2	99,216	44,096	1,378	444	444	7,992	12	1,164

Notes:

- 7 speed grade devices are not available in Industrial grade.
- Logic Cell ≈ (1) 4-input LUT + (1)FF + Carry Logic
- These devices can be ordered in a configuration without RocketIO transceivers. See [Table 3](#) for package configurations.
- Virtex-II Pro X devices equipped with RocketIO X transceiver cores.

RocketIO X Transceiver Features (XC2VPX20 and XC2VPX70 Only)

- Variable-Speed Full-Duplex Transceiver (XC2VPX20) Allowing 2.488 Gb/s to 6.25 Gb/s Baud Transfer Rates.
 - Includes specific baud rates used by various standards, as listed in [Table 4, Module 2](#).
- Fixed-Speed Full-Duplex Transceiver (XC2VPX70) Operating at 4.25 Gb/s Baud Transfer Rate.
- Eight or Twenty Transceiver Modules on an FPGA, Depending upon Device
- Monolithic Clock Synthesis and Clock Recovery
 - Eliminates the need for external components
- Automatic Lock-to-Reference Function
- Programmable Serial Output Differential Swing
 - 200 mV to 1600 mV, peak-peak
 - Allows compatibility with other serial system voltage levels
- Programmable Pre-emphasis Levels 0 to 500%
- Telecom/Datacom Support Modes
 - "x8" and "x10" clocking/data paths
 - 64B/66B clocking support

- Programmable Receiver Equalization
- Internal AC Coupling
- On-Chip 50Ω Termination
 - Eliminates the need for external termination resistors
- Pre- and Post-Driver Serial and Parallel TX-to-RX
- Internal Loopback Modes for Testing Operability
- Programmable Comma Detection
 - Allows for any protocol
 - Allows for detection of any 10-bit character
- 8B/10B and 64B/66B Encoding Blocks

RocketIO Transceiver Features (All Except XC2VPX20 and XC2VPX70)

- Full-Duplex Serial Transceiver (SERDES) Capable of Baud Rates from 600 Mb/s to 3.125 Gb/s
- 100 Gb/s Duplex Data Rate (20 Channels)
- Monolithic Clock Synthesis and Clock Recovery (CDR)
- Fibre Channel, 10G Fibre Channel, Gigabit Ethernet, 10 Gb Attachment Unit Interface (XAUI), and Infiniband-Compliant Transceivers
- 8-, 16-, or 32-bit Selectable Internal FPGA Interface
- 8B/10B Encoder and Decoder (optional)
- 50Ω / 75Ω on-chip Selectable Transmit and Receive Terminations
- Programmable Comma Detection
- Channel Bonding Support (from 2 to 20 Channels)
- Rate Matching via Insertion/Deletion Characters
- Four Levels of Selectable Pre-Emphasis
- Five Levels of Output Differential Voltage
- Per-Channel Internal Loopback Modes
- 2.5V Transceiver Supply Voltage

PowerPC RISC Processor Block Features (All Except XC2VP2)

- Embedded 300+ MHz Harvard Architecture Block
- Low Power Consumption: 0.9 mW/MHz
- Five-Stage Data Path Pipeline
- Hardware Multiply/Divide Unit
- Thirty-Two 32-bit General Purpose Registers
- 16 KB Two-Way Set-Associative Instruction Cache
- 16 KB Two-Way Set-Associative Data Cache
- Memory Management Unit (MMU)
 - 64-entry unified Translation Look-aside Buffers (TLB)
 - Variable page sizes (1 KB to 16 MB)
- Dedicated On-Chip Memory (OCM) Interface
- Supports IBM CoreConnect™ Bus Architecture
- Debug and Trace Support
- Timer Facilities

Virtex-II Pro Platform FPGA Technology (All Devices)

- SelectRAM+ Memory Hierarchy
 - Up to 8 Mb of True Dual-Port RAM in 18 Kb block SelectRAM+ resources
 - Up to 1,378 Kb of distributed SelectRAM+ resources
 - High-performance interfaces to external memory
- Arithmetic Functions
 - Dedicated 18-bit x 18-bit multiplier blocks
 - Fast look-ahead carry logic chains
- Flexible Logic Resources
 - Up to 88,192 internal registers/latches with Clock Enable
 - Up to 88,192 look-up tables (LUTs) or cascadable variable (1 to 16 bits) shift registers
 - Wide multiplexers and wide-input function support
 - Horizontal cascade chain and Sum-of-Products support
 - Internal 3-state busing
- High-Performance Clock Management Circuitry
 - Up to twelve Digital Clock Manager (DCM) modules
 - Precise clock de-skew
- Flexible frequency synthesis
 - High-resolution phase shifting
 - 16 global clock multiplexer buffers in all parts
- Active Interconnect Technology
 - Fourth-generation segmented routing structure
 - Fast, predictable routing delay, independent of fanout
 - Deep sub-micron noise immunity benefits
- SelectIO™-Ultra Technology
 - Up to 1,164 user I/Os
 - Twenty-two single-ended standards and ten differential standards
 - Programmable LVCMOS sink/source current (2 mA to 24 mA) per I/O
 - XCITE Digitally Controlled Impedance (DCI) I/O
 - PCI/PCI-X support ⁽¹⁾
 - Differential signaling
 - 840 Mb/s Low-Voltage Differential Signaling I/O (LVDS) with current mode drivers
 - On-chip differential termination
 - Bus LVDS I/O

1. Refer to [XAPP653](#) for more information.

- HyperTransport (LDT) I/O with current driver buffers
 - Built-in DDR input and output registers
- Proprietary high-performance SelectLink technology for communications between Xilinx devices
 - High-bandwidth data path
 - Double Data Rate (DDR) link
 - Web-based HDL generation methodology
- SRAM-Based In-System Configuration
 - Fast SelectMAP™ configuration
 - Triple Data Encryption Standard (DES) security option (bitstream encryption)
 - IEEE 1532 support
 - Partial reconfiguration
 - Unlimited reprogrammability
- Readback capability
- Supported by Xilinx Foundation™ and Alliance Series™ Development Systems
 - Integrated VHDL and Verilog design flows
 - ChipScope™ Integrated Logic Analyzer
- 0.13 μm Nine-Layer Copper Process with 90 nm High-Speed Transistors
- 1.5V (V_{CCINT}) core power supply, dedicated 2.5V V_{CCAUX} auxiliary and V_{CCO} I/O power supplies
- IEEE 1149.1 Compatible Boundary-Scan Logic Support
- Flip-Chip and Wire-Bond Ball Grid Array (BGA) Packages in Standard 1.00 mm Pitch.
- Wire-Bond BGA Devices Available in Pb-Free Packaging (www.xilinx.com/pbfree)
- Each Device 100% Factory Tested

General Description

The Virtex-II Pro and Virtex-II Pro X families contain platform FPGAs for designs that are based on IP cores and customized modules. The family incorporates multi-gigabit transceivers and PowerPC CPU blocks in Virtex-II Pro Series FPGA architecture. It empowers complete solutions for telecommunication, wireless, networking, video, and DSP applications.

The leading-edge 0.13 μm CMOS nine-layer copper process and Virtex-II Pro architecture are optimized for high performance designs in a wide range of densities. Combining a wide variety of flexible features and IP cores, the Virtex-II Pro family enhances programmable logic design capabilities and is a powerful alternative to mask-programmed gate arrays.

Architecture

Array Overview

Virtex-II Pro and Virtex-II Pro X devices are user-programmable gate arrays with various configurable elements and embedded blocks optimized for high-density and high-performance system designs. Virtex-II Pro devices implement the following functionality:

- Embedded high-speed serial transceivers enable data bit rate up to 3.125 Gb/s per channel (RocketIO) or 6.25 Gb/s (RocketIO X).
- Embedded IBM PowerPC 405 RISC processor blocks provide performance up to 400 MHz.
- SelectIO-Ultra blocks provide the interface between package pins and the internal configurable logic. Most popular and leading-edge I/O standards are supported by the programmable IOBs.
- Configurable Logic Blocks (CLBs) provide functional elements for combinatorial and synchronous logic, including basic storage elements. BUFTs (3-state buffers) associated with each CLB element drive dedicated segmentable horizontal routing resources.

- Block SelectRAM+ memory modules provide large 18 Kb storage elements of True Dual-Port RAM.
- Embedded multiplier blocks are 18-bit x 18-bit dedicated multipliers.
- Digital Clock Manager (DCM) blocks provide self-calibrating, fully digital solutions for clock distribution delay compensation, clock multiplication and division, and coarse- and fine-grained clock phase shifting.

A new generation of programmable routing resources called Active Interconnect Technology interconnects all these elements. The general routing matrix (GRM) is an array of routing switches. Each programmable element is tied to a switch matrix, allowing multiple connections to the general routing matrix. The overall programmable interconnection is hierarchical and supports high-speed designs.

All programmable elements, including the routing resources, are controlled by values stored in static memory cells. These values are loaded in the memory cells during configuration and can be reloaded to change the functions of the programmable elements.

Features

This section briefly describes Virtex-II Pro / Virtex-II Pro X features. For more details, refer to [Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Functional Description](#).

RocketIO / RocketIO X MGT Cores

The RocketIO and RocketIO X Multi-Gigabit Transceivers are flexible parallel-to-serial and serial-to-parallel embedded transceiver cores used for high-bandwidth interconnection between buses, backplanes, or other subsystems.

Multiple user instantiations in an FPGA are possible, providing up to 100 Gb/s (RocketIO) or 170 Gb/s (RocketIO X) of full-duplex raw data transfer. Each channel can be operated at a maximum data transfer rate of 3.125 Gb/s (RocketIO) or 6.25 Gb/s (RocketIO X).

Each RocketIO or RocketIO X core implements the following technology:

- Serializer and deserializer (SERDES)
- Monolithic clock synthesis and clock recovery (CDR)
- 10 Gigabit Attachment Unit Interface (XAUI) Fibre Channel (3.1875 Gb/s XAUI), Infiniband, PCI Express, Aurora, SXI-5 (SFI-5,/SPI-5), and OC-48 compatibility⁽¹⁾
- 8/16/32-bit (RocketIO) or 8/16/32/64-bit (RocketIO X) selectable FPGA interface
- 8B/10B (RocketIO) or 8B/10B and 64B/66B (RocketIO X) encoder and decoder with bypassing option on each channel
- Channel bonding support (two to twenty channels)
 - Elastic buffers for inter-chip deskewing and channel-to-channel alignment
- Receiver clock recovery tolerance of up to 75 non-transitioning bits
- 50Ω (RocketIO X) or 50Ω / 75Ω selectable (RocketIO) on-chip transmit and receive terminations
- Programmable comma detection and word alignment
- Rate matching via insertion/deletion characters
- Automatic lock-to-reference function
- Programmable pre-emphasis support
- Per-channel serial and parallel transmitter-to-receiver internal loopback modes
- Optional transmit and receive data inversion
- Cyclic Redundancy Check support (RocketIO only)

PowerPC 405 Processor Block

The PPC405 RISC CPU can execute instructions at a sustained rate of one instruction per cycle. On-chip instruction and data cache reduce design complexity and improve system throughput.

The PPC405 features include:

- PowerPC RISC CPU
 - Implements the PowerPC User Instruction Set Architecture (UISA) and extensions for embedded applications
 - Thirty-two 32-bit general purpose registers (GPRs)
 - Static branch prediction
 - Five-stage pipeline with single-cycle execution of most instructions, including loads/stores
 - Unaligned and aligned load/store support to cache, main memory, and on-chip memory
 - Hardware multiply/divide for faster integer arithmetic (4-cycle multiply, 35-cycle divide)
 - Enhanced string and multiple-word handling
 - Big/little endian operation support
- Storage Control

- Separate instruction and data cache units, both two-way set-associative and non-blocking
- Eight words (32 bytes) per cache line
- 16 KB array Instruction Cache Unit (ICU), 16 KB array Data Cache Unit (DCU)
- Operand forwarding during instruction cache line fill
- Copy-back or write-through DCU strategy
- Doubleword instruction fetch from cache improves branch latency
- Virtual mode memory management unit (MMU)
 - Translation of the 4 GB logical address space into physical addresses
 - Software control of page replacement strategy
 - Supports multiple simultaneous page sizes ranging from 1 KB to 16 MB
- OCM controllers provide dedicated interfaces between Block SelectRAM+ memory and processor block instruction and data paths for high-speed access
- PowerPC timer facilities
 - 64-bit time base
 - Programmable interval timer (PIT)
 - Fixed interval timer (FIT)
 - Watchdog timer (WDT)
- Debug Support
 - Internal debug mode
 - External debug mode
 - Debug Wait mode
 - Real Time Trace debug mode
 - Enhanced debug support with logical operators
 - Instruction trace and trace-back support
 - Forward or backward trace
- Two hardware interrupt levels support
- Advanced power management support

Input/Output Blocks (IOBs)

IOBs are programmable and can be categorized as follows:

- Input block with an optional single data rate (SDR) or double data rate (DDR) register
- Output block with an optional SDR or DDR register and an optional 3-state buffer to be driven directly or through an SDR or DDR register
- Bidirectional block (any combination of input and output configurations)

These registers are either edge-triggered D-type flip-flops or level-sensitive latches.

IOBs support the following single-ended I/O standards:

- LVTTTL, LVCMOS (3.3V,⁽²⁾ 2.5V, 1.8V, and 1.5V)
- PCI-X compatible (133 MHz and 66 MHz) at 3.3V⁽³⁾
- PCI compliant (66 MHz and 33 MHz) at 3.3V⁽³⁾
- GTL and GTLP

1. Refer to [Table 4, Module 2](#) for detailed information about RocketIO and RocketIO X transceiver compatible protocols.

2. Refer to [XAPP659](#) for more information.

3. Refer to [XAPP653](#) for more information.

- HSTL (1.5V and 1.8V, Class I, II, III, and IV)
- SSTL (1.8V and 2.5V, Class I and II)

The DCI I/O feature automatically provides on-chip termination for each single-ended I/O standard.

The IOB elements also support the following differential signaling I/O standards:

- LVDS and Extended LVDS (2.5V)
- BLVDS (Bus LVDS)
- ULVDS
- LDT
- LVPECL (2.5V)

Two adjacent pads are used for each differential pair. Two or four IOBs connect to one switch matrix to access the routing resources. On-chip differential termination is available for LVDS, LVDS Extended, ULVDS, and LDT standards.

Configurable Logic Blocks (CLBs)

CLB resources include four slices and two 3-state buffers. Each slice is equivalent and contains:

- Two function generators (F & G)
- Two storage elements
- Arithmetic logic gates
- Large multiplexers
- Wide function capability
- Fast carry look-ahead chain
- Horizontal cascade chain (OR gate)

The function generators F & G are configurable as 4-input look-up tables (LUTs), as 16-bit shift registers, or as 16-bit distributed SelectRAM+ memory.

In addition, the two storage elements are either edge-triggered D-type flip-flops or level-sensitive latches.

Each CLB has internal fast interconnect and connects to a switch matrix to access general routing resources.

Block SelectRAM+ Memory

The block SelectRAM+ memory resources are 18 Kb of True Dual-Port RAM, programmable from 16K x 1 bit to 512 x 36 bit, in various depth and width configurations. Each port is totally synchronous and independent, offering three "read-during-write" modes. Block SelectRAM+ memory is cascadable to implement large embedded storage blocks. Supported memory configurations for dual-port and single-port modes are shown in [Table 2](#).

Table 2: Dual-Port and Single-Port Configurations

16K x 1 bit	4K x 4 bits	1K x 18 bits
8K x 2 bits	2K x 9 bits	512 x 36 bits

18 X 18 Bit Multipliers

A multiplier block is associated with each SelectRAM+ memory block. The multiplier block is a dedicated 18 x 18-bit 2s complement signed multiplier, and is opti-

mized for operations based on the block SelectRAM+ content on one port. The 18 x 18 multiplier can be used independently of the block SelectRAM+ resource. Read/multiply/accumulate operations and DSP filter structures are extremely efficient.

Both the SelectRAM+ memory and the multiplier resource are connected to four switch matrices to access the general routing resources.

Global Clocking

The DCM and global clock multiplexer buffers provide a complete solution for designing high-speed clock schemes.

Up to twelve DCM blocks are available. To generate deskewed internal or external clocks, each DCM can be used to eliminate clock distribution delay. The DCM also provides 90-, 180-, and 270-degree phase-shifted versions of its output clocks. Fine-grained phase shifting offers high-resolution phase adjustments in increments of $1/256$ of the clock period. Very flexible frequency synthesis provides a clock output frequency equal to a fractional or integer multiple of the input clock frequency. For exact timing parameters, see [Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics](#).

Virtex-II Pro devices have 16 global clock MUX buffers, with up to eight clock nets per quadrant. Each clock MUX buffer can select one of the two clock inputs and switch glitch-free from one clock to the other. Each DCM can send up to four of its clock outputs to global clock buffers on the same edge. Any global clock pin can drive any DCM on the same edge.

Routing Resources

The IOB, CLB, block SelectRAM+, multiplier, and DCM elements all use the same interconnect scheme and the same access to the global routing matrix. Timing models are shared, greatly improving the predictability of the performance of high-speed designs.

There are a total of 16 global clock lines, with eight available per quadrant. In addition, 24 vertical and horizontal long lines per row or column, as well as massive secondary and local routing resources, provide fast interconnect. Virtex-II Pro buffered interconnects are relatively unaffected by net fanout, and the interconnect layout is designed to minimize crosstalk.

Horizontal and vertical routing resources for each row or column include:

- 24 long lines
- 120 hex lines
- 40 double lines
- 16 direct connect lines (total in all four directions)

Boundary Scan

Boundary-scan instructions and associated data registers support a standard methodology for accessing and configuring Virtex-II Pro devices, complying with IEEE standards 1149.1 and 1532. A system mode and a test mode are

implemented. In system mode, a Virtex-II Pro device will continue to function while executing non-test Boundary-Scan instructions. In test mode, Boundary-Scan test instructions control the I/O pins for testing purposes. The Virtex-II Pro Test Access Port (TAP) supports BYPASS, PRELOAD, SAMPLE, IDCODE, and USERCODE non-test instructions. The EXTEST, INTEST, and HIGHZ test instructions are also supported.

Configuration

Virtex-II Pro / Virtex-II Pro devices are configured by loading the bitstream into internal configuration memory using one of the following modes:

- Slave-serial mode
- Master-serial mode
- Slave SelectMAP mode
- Master SelectMAP mode
- Boundary-Scan mode (IEEE 1532)

A Data Encryption Standard (DES) decryptor is available on-chip to secure the bitstreams. One or two triple-DES key sets can be used to optionally encrypt the configuration data.

The Xilinx System Advanced Configuration Environment (System ACE) family offers high-capacity and flexible solution for FPGA configuration as well as program/data storage for the processor. See [DS080](#), *System ACE CompactFlash Solution* for more information.

Readback and Integrated Logic Analyzer

Configuration data stored in Virtex-II Pro / Virtex-II Pro configuration memory can be read back for verification. Along with the configuration data, the contents of all flip-flops and latches, distributed SelectRAM+, and block SelectRAM+ memory resources can be read back. This capability is useful for real-time debugging.

The Xilinx ChipScope Integrated Logic Analyzer (ILA) cores and Integrated Bus Analyzer (IBA) cores, along with the ChipScope Pro Analyzer software, provide a complete solution for accessing and verifying user designs within Virtex-II Pro devices.

IP Core and Reference Support

Intellectual Property is part of the Platform FPGA solution. In addition to the existing FPGA fabric cores, the list below shows some of the currently available hardware and software intellectual properties specially developed for Virtex-II Pro / Virtex-II Pro X by Xilinx. Each IP core is modular, portable, Real-Time Operating System (RTOS) independent, and CoreConnect compatible for ease of design migration. Refer to www.xilinx.com/ipcenter for the latest and most complete list of cores.

Hardware Cores

- Bus Infrastructure cores (arbiters, bridges, and more)
- Memory cores (DDR, Flash, and more)
- Peripheral cores (UART, IIC, and more)
- Networking cores (ATM, Ethernet, and more)

Software Cores

- Boot code
- Test code
- Device drivers
- Protocol stacks
- RTOS integration
- Customized board support package

Virtex-II Pro / Virtex-II Pro X Device/Package Combinations and Maximum I/Os

Offerings include ball grid array (BGA) packages with 1.0 mm pitch. In addition to traditional wire-bond interconnect (FG/FGG packages), flip-chip interconnect (FF packages) is used in some of the BGA offerings. Flip-chip interconnect construction supports more I/Os than are possible in wire-bond versions of similar packages, providing a high pin count and excellent power dissipation.

The device/package combination table ([Table 3](#)) details the maximum number of user I/Os and RocketIO / RocketIO X MGTs for each device and package using wire-bond or flip-chip technology.

The FF1148 and FF1696 packages have no RocketIO transceivers bonded out. Extra SelectIO-Ultra resources occupy available pins in these packages, resulting in a higher user I/O count. These packages are available for the XC2VP40, XC2VP50, and XC2VP100 devices only.

The I/Os per package count includes all user I/Os except the 15 control pins (CCLK, DONE, M0, M1, M2, PROG_B, PWRDWN_B, TCK, TDI, TDO, TMS, HSWAP_EN, DXN, DXP, and RSVD), VBATT, and the RocketIO / RocketIO X transceiver pins.

Table 3: Virtex-II Pro Device/Package Combinations and Maximum Number of Available I/Os

Package ⁽¹⁾	FG256/ FGG256	FG456/ FGG456	FG676	FF672	FF896	FF1152	FF1148	FF1517	FF1704	FF1696
Pitch (mm)	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.00
Size (mm)	17 x 17	23 x 23	26 x 26	27 x 27	31 x 31	35 x 35	35 x 35	40 x 40	42.5 x 42.5	42.5 x 42.5
XC2VP2	140 / 4	156 / 4		204 / 4						
XC2VP4	140 / 4	248 / 4		348 / 4						
XC2VP7		248 / 8		396 / 8	396 / 8					
XC2VP20			404 / 8		556 / 8	564 / 8				
XC2VPX20					552 / 8 ⁽²⁾					
XC2VP30			416 / 8		556 / 8	644 / 8				
XC2VP40			416 / 8			692 / 12	804 / 0 ⁽³⁾			
XC2VP50						692 / 16	812 / 0 ⁽³⁾	852 / 16		
XC2VP70								964 / 16	996 / 20	
XC2VPX70									992 / 20 ⁽²⁾	
XC2VP100									1,040 / 20	1,164 / 0 ⁽³⁾

Notes:

- Wirebond packages FG256, FG456, and FG676 are also available in Pb-free versions FGG256, FGG456, and FGG676. See [Virtex-II Pro Ordering Examples](#) for details on how to order.
- Virtex-II Pro X device is equipped with RocketIO X transceiver cores.
- The RocketIO transceivers in devices in the FF1148 and FF1696 packages are not bonded out to the package pins.

Maximum Performance

Maximum performance of the RocketIO / RocketIO X transceiver and the PowerPC processor block varies, depending on package style and speed grade. See [Table 4](#) for details. [Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics](#) contains the rest of the FPGA fabric performance parameters.

Table 4: Maximum RocketIO / RocketIO X Transceiver and Processor Block Performance

Device	Speed Grade			Units
	-7 ⁽¹⁾	-6	-5	
RocketIO X Transceiver FlipChip (FF)	N/A	6.25 ⁽³⁾	4.25 ⁽³⁾	Gb/s
RocketIO Transceiver FlipChip (FF)	3.125	3.125	2.0	Gb/s
RocketIO Transceiver Wirebond (FG)	2.5	2.5	2.0	Gb/s
PowerPC Processor Block	400 ⁽²⁾	350 ⁽²⁾	300	MHz

Notes:

- 7 speed grade devices are not available in Industrial grade.
- IMPORTANT!** When CPMC405CLOCK runs at speeds greater than 350 MHz in -7 Commercial grade dual-processor devices, or greater than 300 MHz in -6 Industrial grade dual-processor devices, users must implement the technology presented in [XAPP755](#), "PowerPC 405 Clock Macro for -7(C) and -6(I) Speed Grade Dual-Processor Devices." Refer to [Table 1](#) to identify dual-processor devices.
- XC2VPX70 is only available at fixed 4.25 Gb/s baud rate.

Virtex-II Pro Ordering Examples

Virtex-II Pro ordering examples are shown in **Figure 1** (flip-chip package) and **Figure 2** (Pb-free wire-bond package).

Example: XC2VP40 -7 FF 1152 C

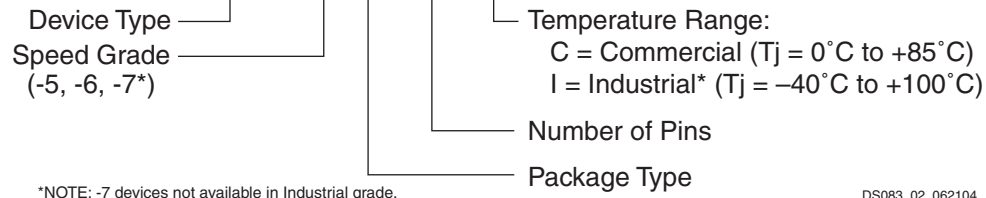


Figure 1: Virtex-II Pro Ordering Example, Flip-Chip Package

Example: XC2VP40 -6 FG G 676 I

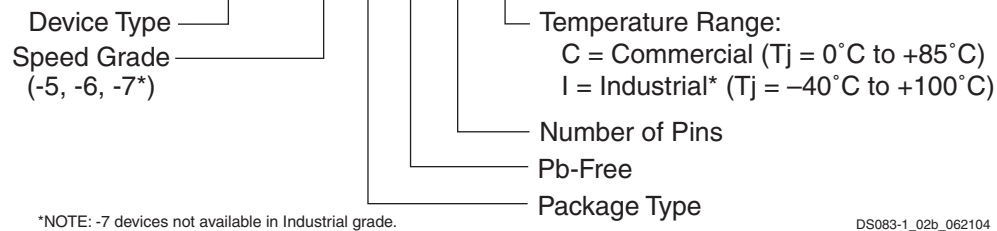


Figure 2: Virtex-II Pro Ordering Example, Pb-Free Wire-Bond Package

Virtex-II Pro X Ordering Example

A Virtex-II Pro X ordering example is shown in **Figure 3**.

Example: XC2VPX20 -6 FF 896 C

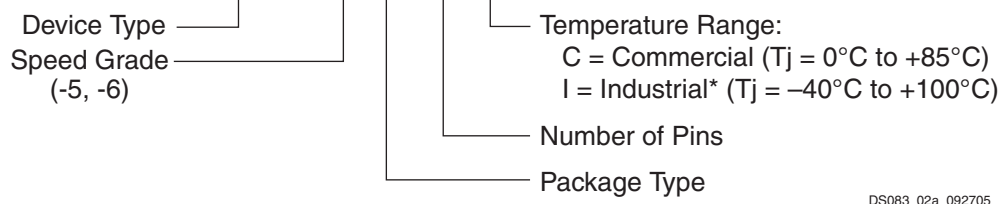


Figure 3: Virtex-II Pro X Ordering Example, Flip-Chip Package

Revision History

This section records the change history for this module of the data sheet.

Date	Version	Revision
01/31/02	1.0	Initial Xilinx release.
06/13/02	2.0	New Virtex-II Pro family members. New timing parameters per speedsfile v1.62 .
09/03/02	2.1	Updates to Table 1 and Table 3 . Processor Block information added to Table 4 .
09/27/02	2.2	In Table 1 , correct max number of XC2VP30 I/Os to 644.
11/20/02	2.3	Add bullet items for 3.3V I/O features.
01/20/03	2.4	- In Table 3, add FG676 package option for XC2VP20, XC2VP30, and XC2VP40. - Remove FF1517 package option for XC2VP40.
03/24/03	2.4.1	- Correct number of single-ended I/O standards from 19 to 22. - Correct minimum RocketIO serial speed from 622 Mbps to 600 Mbps.
08/25/03	2.4.2	Add footnote referring to XAPP659 to callout for 3.3V I/O standards on page 4.
12/10/03	3.0	XC2VP2 through XC2VP70 speed grades -5, -6, and -7, and XC2VP100 speed grades -5 and -6, are released to Production status.
02/19/04	3.1	Table 1: Corrected number of RocketIO transceiver blocks for XC2VP40. - Section Virtex-II Pro Platform FPGA Technology (All Devices): Updated number of differential standards supported from six to ten. - Section Input/Output Blocks (IOBs): Added text stating that differential termination is available for LVDS, LVDS Extended, ULVDS, and LDT standards. Figure 1: Added note stating that -7 devices are not available in Industrial grade.
03/09/04	3.1.1	Recompiled for backward compatibility with Acrobat 4 and above. No content changes.
06/30/04	4.0	Merged in DS110-1 (Module 1 of Virtex-II Pro X data sheet). Added information on available Pb-free packages.
11/17/04	4.1	<i>No changes in Module 1 for this revision.</i>
03/01/05	4.2	Table 3 : Corrected number of RocketIO transceivers for XC2VP7-FG456.
06/20/05	4.3	<i>No changes in Module 1 for this revision.</i>
09/15/05	4.4	- Changed all instances of 10.3125 Gb/s (RocketIO transceiver maximum bit rate) to 6.25 Gb/s. - Changed all instances of 412.5 Gb/s (RocketIO X transceiver maximum multi-channel raw data transfer rate) to 250 Gb/s.
10/10/05	4.5	- Changed XC2VPX70 variable baud rate specification to fixed-rate operation at 4.25 Gb/s. - Changed maximum performance for -7 Virtex-II Pro X MGT (Table 4) to N/A.
03/05/07	4.6	<i>No changes in Module 1 for this revision.</i>
11/05/07	4.7	Updated copyright notice and legal disclaimer.
06/21/11	5.0	Added <i>Product Not Recommended for New Designs</i> banner.

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Virtex-II Pro Data Sheet

The Virtex-II Pro Data Sheet contains the following modules:

- **Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Introduction and Overview (Module 1)**
- **Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Functional Description (Module 2)**
- **Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics (Module 3)**
- **Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Pinout Information (Module 4)**